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Abstract A photo-curable resin composition for sealing material, which is superior in the photo-curing performance and in the prompt curing property and is better in the adhesive property, in the resistance to moisture permeation and in the heat resistance, the photo-curable resin composition comprising (A) a compound having oxetane ring, (B) a photoinitiator for cationic polymerization and (C) a silane coupling agent, wherein the composition has a viscosity in the range from 0.01 to 300 Pa.s at 25 DEG C.